PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yu-Chia Lai	07/01/2013
Hsien-Ming Tu	07/01/2013
Tung-Liang Shao	07/01/2013
Hsien-Wei Chen	07/01/2013
Chang-Pin Huang	07/01/2013
Ching-Jung Yang	07/01/2013

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Co., LTD
Street Address:	No.8, Li-Hsin Rd.6, Science-Based Industrial Park
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13940626

OP $40.00 13940626

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	28503-007
NAME OF SUBMITTER:	Steven J. Laureanti

Signature:	/Steven J. Laureanti/
Date:	08/06/2013
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NP-13873-US-B
TSMC-2-13-0588

Inventor(s)-to-Assignee

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title)________
Self-alignment Structure for Wafer Level Chip Scale Package

The PATENT RIGHTS referred to in this agreement are:

(*check one*) ☐a patent application for this invention, executed by the ASSIGNOR(S) concurrently with this assignment.

☒U.S. patent application Serial No.13/940,626, filed July 12, 2013

☐a U.S. patent application based on PCT International Application No.______________filed on (date)______________(U.S. patent application Serial No._____________, if known).

☐U.S. patent No._____, issued_____.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

(*check one*) ☒U.S. patent rights only.

☐Worldwide patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date of any U.S. or foreign patent application for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(*Name of Assignee*) TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.

(*Address*) NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN 300, R.O.C.

The ASSIGNEE is:

(*check one*)☐An individual.

☐A Partnership.

☒A Corporation of TAIWAN, R.O.C. (*specify state or country*)

☐(other)______________________________________

The ASSIGNOR(S), in consideration of $10.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, hereby assign(s) the following rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable provisions, based on any earlier patent applications for this invention.

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THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO
ASSIGNEE: TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
INVENTION TITLE: Self-alignment Structure for Wafer Level Chip Scale Package

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Yu-Chia LAI	Yu-Chia LAI	2013/7/1
Name of sole or first inventor	Signature	Date
Hsien-Ming TU	Hsien-Ming Tu	2013/7/1
Name of second inventor, if any	Signature	Date
Tung-Liang SHAO	Tung-Liang Shao	2013/7/1
Name of third inventor, if any	Signature	Date
Hsien-Wei CHEN	Hsien-Wei Chen	2013.7.1
Name of fourth inventor, if any	Signature	Date
Chang-Pin HUANG	Chang-Pin HUANG	2013/7/1
Name of fifth inventor, if any	Signature	Date
Ching-Jung YANG	Ching-Jung Yang	2013/7/1
Name of sixth inventor, if any	Signature	Date